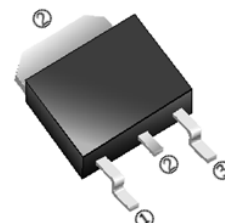


RoHS Compliant Product  
A suffix of "-C" specifies halogen free

## DESCRIPTION

These N-Channel enhancement mode power field effect transistors are using advanced trench technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### TO-252(D-Pack)



## FEATURES

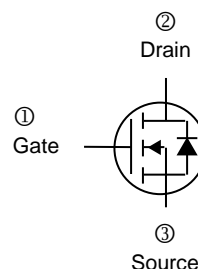
- Fast Switching
- Green Device Available

## PACKAGE INFORMATION

Package	MPQ	Leader Size
TO-252	2.5K	13 inch

## ORDER INFORMATION

Part Number	Type
SSD13N10-C	Lead (Pb)-free and Halogen-free



## ABSOLUTE MAXIMUM RATINGS ( $T_A=25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DS}$	100	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$I_D$	13	A
Pulsed Drain Current <sup>1</sup>	$I_{DM}$	52	A
Power Dissipation	$P_D$	39	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55~150	$^{\circ}\text{C}$
<b>Thermal Resistance Rating</b>			
Thermal Resistance Junction-Ambient	$R_{\theta JA}$	52	$^{\circ}\text{C}/\text{W}$
Thermal Resistance Junction-Case	$R_{\theta JC}$	3.2	

**ELECTRICAL CHARACTERISTICS** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Drain-Source Breakdown Voltage	$BV_{DSS}$	100	-	-	V	$V_{GS}=0, I_D=250\mu\text{A}$
Gate-Threshold Voltage	$V_{GS(th)}$	1	-	2.5	V	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$
Gate-Source Leakage Current	$I_{GSS}$	-	-	$\pm 100$	nA	$V_{GS}=\pm 20\text{V}, V_{DS}=0\text{V}$
Drain-Source Leakage Current	$I_{DSS}$	-	-	1	$\mu\text{A}$	$V_{DS}=100\text{V}, V_{GS}=0$
Static Drain-Source On-Resistance	$R_{DS(ON)}$	-	-	130	m $\Omega$	$V_{GS}=10\text{V}, I_D=6\text{A}$
		-	-	190		$V_{GS}=4.5\text{V}, I_D=3\text{A}$
Gate Resistance	$R_g$	-	7.2	-	$\Omega$	$V_{DS}=V_{GS}=0, f=1\text{MHz}$
Total Gate Charge	$Q_g$	-	4	-	nC	$V_{DS}=50\text{V}$ $V_{GS}=10\text{V}$ $I_D=6\text{A}$
Gate-Source Charge	$Q_{gs}$	-	0.9	-		
Gate-Drain Change	$Q_{gd}$	-	1.1	-		
Turn-on Delay Time	$T_{d(on)}$	-	12.6	-	nS	$V_{DD}=50\text{V}$ $V_{GS}=10\text{V}$ $I_D=6\text{A}$ $R_G=3\Omega$
Rise Time	$T_r$	-	19	-		
Turn-off Delay Time	$T_{d(off)}$	-	20	-		
Fall Time	$T_f$	-	27.8	-		
Input Capacitance	$C_{iss}$	-	195	-	pF	$V_{DS}=50\text{V}$ $V_{GS}=0$ $f=1\text{MHz}$
Output Capacitance	$C_{oss}$	-	31	-		
Reverse Transfer Capacitance	$C_{rss}$	-	2.5	-		
<b>Source-Drain Diode</b>						
Continuous Source Current	$I_S$	-	-	13	A	
Diode Forward Voltage <sup>2</sup>	$V_{SD}$	-	-	1.2	V	$I_S=10\text{A}, V_{GS}=0$

Notes:

1. Repetitive rating : pulse width limited by max. junction temperature.
2. The data tested by pulsed, pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .

**CHARACTERISTIC CURVES**

FIG. 1-Transfer Characteristics

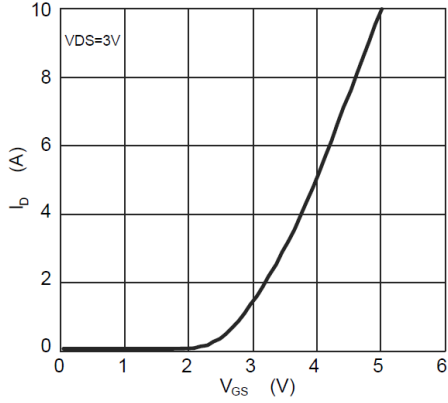


FIG. 2- $I_S$  vs.  $V_{SD}$

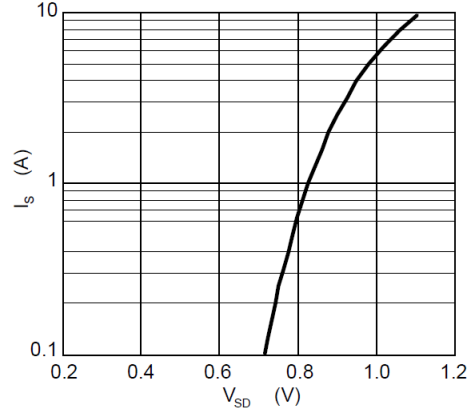


FIG. 3- $R_{DS(ON)}$  vs.  $I_D$

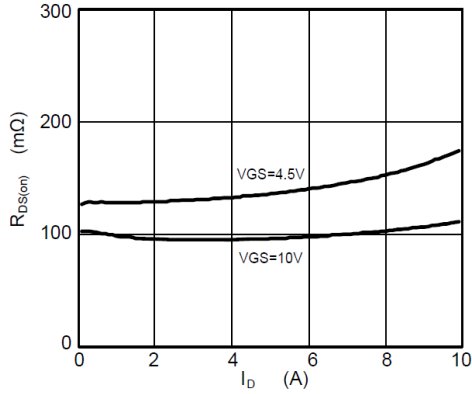


FIG. 4-Normalized  $R_{DS(ON)}$  vs.  $T_J$

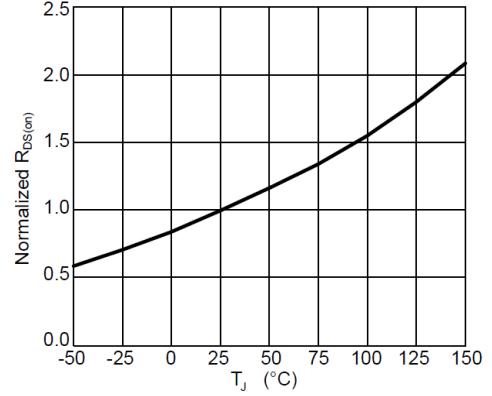


FIG. 5-Gate Charge Characteristics

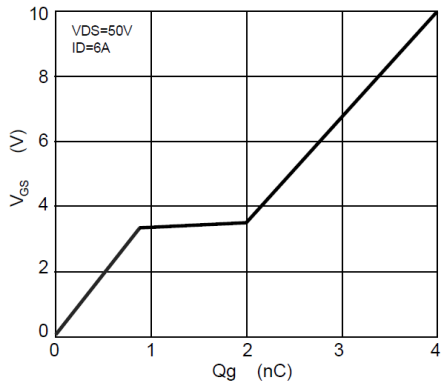


FIG. 6- $P_D$  vs.  $T_C$

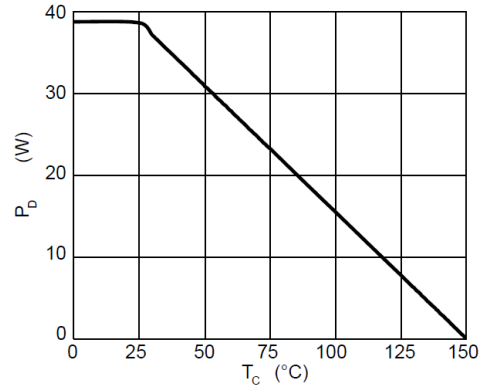
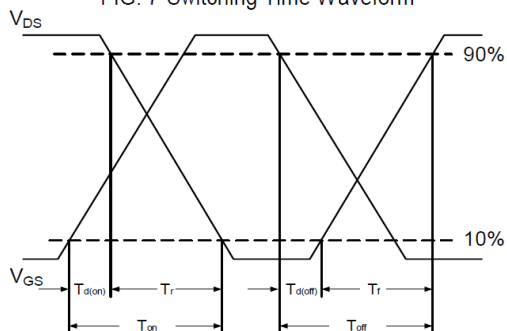
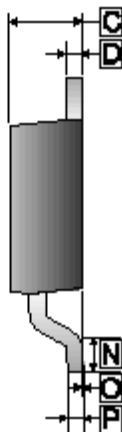
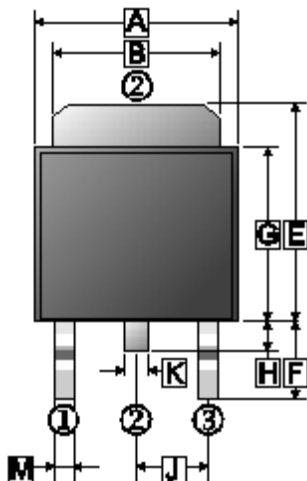


FIG. 7-Switching Time Waveform



**PACKAGE OUTLINE DIMENSIONS**

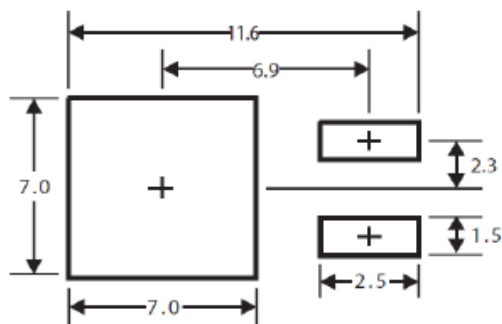
TO-252



REF.	Millimeter	
	Min.	Max.
A	6.30	6.90
B	4.95	5.53
C	2.10	2.50
D	0.35	0.90
E	6.00	7.70
F	2.90 REF.	
G	5.30	6.40
H	0.60	1.20
J	2.30 REF.	
K	0.89 REF.	
M	0.45	1.14
N	1.55 TYP.	
O	0	0.15
P	0.58 REF.	

**MOUNTING PAD LAYOUT**

TO-252



\*Dimensions in millimeters